

INCH-POUND

MIL-PRF-39007H
AMENDMENT 2
23 March 1999
SUPERSEDING
AMENDMENT 1
4 February 1999

PERFORMANCE SPECIFICATION

RESISTORS, FIXED, WIRE WOUND (POWER TYPE),
NONESTABLISHED RELIABILITY, ESTABLISHED RELIABILITY, AND SPACE LEVEL
GENERAL SPECIFICATION FOR

This amendment forms a part of MIL-PRF-39007H, dated 3 July 1997, and is approved for use by all Departments and Agencies of the Department of Defense.

PAGE 6

2.2.1 STANDARDS, parenthetical source statement, delete "Defense Printing Service Detachment Office, Building 4D, Customer Service" and substitute "Defense Automated Printing Service, Bldg. 4D (DPM-DODSSP)".

PAGE 8

3.4, delete and substitute:

"3.4 Material. A material shall be used which will enable the resistors to meet the performance requirements of this specification. Acceptance or approval of any constituent material shall not be construed as a guarantee of the acceptance of the finish product. In addition, for space level only, materials use in the manufacturing of the resistor shall meet the outgassing requirement (see 3.26)."

PAGE 9

3.5.1, last line delete "moister" and substitute "moisture".

3.5.6, second line, after solder dip process, add, "(see appendix)".

PAGE 10

3.5.6.1, and 3.5.6.2, delete.

PAGE 14

* 3.27, delete and substitute

"3.27 Radiographic inspection (space level only). When resistors are tested as specified in 4.8.21, they shall exhibit no evidence of defectives (see appendix C, figure 6). All testing shall be done in accordance with appendix C."

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4.6.3.2.4, fourth line, delete "table XIV" and substitute "table XIII".

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4.8.1, last line, after requirements, add "for space level product (T) only, visual inspection shall be performed at 20X."

PAGE 40

6.12.1, delete.

PAGE 41

TABLE XIX, delete.

PAGE 44

After A.4.2, add section 5:

"A.5. SOLDER DIP (RETNING) LEADS

A.5.1 Solder dip (retinning) leads. The manufacturer (or their authorized category B or category C distributor) may solder dip/retin the leads of product supplied to this specification provided the solder dip process (see A.5.2) or an equivalent process has been approved by the qualifying activity.

A.5.2 Qualifying activity approval. Approval of the solder dip process will be based on one of the following options:

- a. When the original lead finish qualified was hot solder dip lead finish 52 of MIL-STD-1276 (NOTE: The 200 microinch maximum thickness is not applicable.) The manufacturer shall use the same solder dip process for retinning as is used in the original manufacture of the product.
- b. When the lead originally qualified was not hot solder dip lead finish 52 of MIL-STD-1276, as prescribed in A.5.2a, approval for the process to be used for solder dip shall be based on the following test procedure:
 - (1) Thirty samples of any resistance value for each style and lead finish are subjected to the manufacturer's solder dip process. Following the solder dip process, the resistors are subjected to the dc resistance test (and other group A electricals). No defects are allowed.
 - (2) Ten of the 30 samples are then subjected to the solderability test. No defects are allowed.
 - (3) The remaining 20 samples are subjected to the resistance to solder heat test followed by the moisture resistance test. No defects are allowed.

A.5.3 Solder dip/retinning options. The manufacturer (or authorized category B or category C distributor) may solder dip/retin as follows:

- a. After the 100 percent group A screening tests: Following the solder dip/retinning process, the dc resistance measurement shall be repeated on 100 percent of the lot. (NOTE: The manufacturer may solder dip/retin prior to the 100 percent electrical measurements of the group A, subgroup 1 tests.) The PDA for the electrical measurements shall be as for the subgroup 1 tests.
- b. As a corrective action: If the lot fails the group A solderability test, the lot may be retinned no more than two times. The lot after retinning shall be 100 percent screened for dc resistance, any parts failing (not exceeding the PDA for group A, subgroup 1 electricals, see 4.6.3.2.1) these screens shall not be supplied to this specification. If electrical failures are detected after the second retinning operation exceeding three percent of the lot, the lot shall not be supplied to this specification.

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- c. After the group A inspection has been completed: Following the solder dip/retrinning process, dc resistance shall be repeated on 100 percent of the lot. The PDA for the electrical measurements shall be as for the subgroup 1 tests. Following these tests, the manufacturer shall submit the lot to the group A solderability test as specified in 4.8.4.”

NOTE: The margins of this amendment are marked with asterisks to indicate where changes from the previous amendment were made. This was done as a convenience only and the Government assumes no liability what so ever for any inaccuracies in these notations. Bidders and contractors are cautioned to evaluate the requirements of this document based on the entire content irrespective of the marginal notations and relationship to the last previous amendment.

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